

## GreensTone PCB capability

Item	Capability
Layers	1-10
Thicker Copper	1-4OZ
Products Type	HF(High-Frequency)&(Radio Frequency) board, Impedance controlled board , HDI board , BGA& Fine Pitch board
Solder Mask	Red, green, yellow,white, blue,black.
Base material	FR4, HI-TG, and so on

Item	Capability
Finished Surface	Conventional HASL, Lead-free HASL, Flash Gold, ENIG (Immersion Gold)OSP(Entek), Immersion Tin, Immersion Silver, Hard Gold
Technical Specification	Minimum line width/gap: 3.5/4mil (laser drill) Minimum hole size: 0.15mm (mechanical drill)/4mil (laser drill) Minimum Annular Ring: 4mil Max Copper thickness: 4OZ Max Production size: 900×1200mm Board Thickness: D/S: 0.2-7.0mm, Multilayers: 0.40-7.0mm, Min Solder Mask Bridge: 0.08mm Aspect ratio: 15:1 Plugging Vias capability: 0.2-0.8mm
Tolerance	Plated holes Tolerance: 0.08mm (min±0.05) Non-plated hole tolerance: 0.05mm (min+0/-0.05mm or +0.05/-0mm) Outline Tolerance: 0.15mm (min±0.10mm) Insulating resistance : 50 ohms (normality) Peel off strength: 1.4N/mm Thermal Stress test : 265°C, 20 seconds Solder mask hardness: 6H E-Test voltage : 500V+15/-0V 30S

Item	Capability
	Warp and Twist: 0.7% (semiconductor test board $\leq$ 0.3% )
Silkscreen	White, Black, None
Panelization	V-scoring, Tab-routing, Tab-routing with Perforation (Stamp Holes
Others	Fly Probe Testing (Free) and A.O.I. testing(free), ISO 9001:2008 ,UL Certificate